



Material Composition Declaration

EPC2219

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/7/2021
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.1 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)		
Chip	Silicon	7440-21-3	0.9382	85.0919	88.0865	850919
	Silicon oxide	7631-86-9	0.0052	0.4749		4749
	Silicon nitride	12033-89-5	0.0015	0.1368		1368
	Gallium nitride	25617-97-4	0.0062	0.5622		5622
	Aluminum	7429-90-5	0.0084	0.7663		7663
	Aluminum nitride	24304-00-5	0.0014	0.1311		1311
	Titanium	7440-32-6	0.0002	0.0193		193
	Titanium nitride	25583-20-4	0.0010	0.0924		924
	Copper	7440-50-8	0.0003	0.0255		255
	Tungsten	7440-33-7	0.0000	0.0037		37
	Polyimide		0.0086	0.7824	7824	
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0072	0.6125	72
	Copper	7440-50-8	0.0067	0.6053		6053
Solder Bump	Tin	7440-50-8	0.1190	10.7924	11.3010	107924
	Silver	7440-02-0	0.0050	0.4520		4520
	Copper	7440-31-5	0.0006	0.0565		565
Sum in total:			1.1025	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.